

[54] **HEAT CURABLE ORGANOPOLYSILOXANE COMPOSITIONS CONTAINING ADHESION ADDITIVES**

[75] Inventors: **Katsutoshi Mine, Ichihara; Minoru Nishio, Chiba; Shinichi Sumimura, Ichihara, all of Japan**

[73] Assignee: **Toray Silicone Company, Ltd., Ichihara, Japan**

[22] Filed: **Oct. 26, 1976**

[21] Appl. No.: **735,721**

[30] **Foreign Application Priority Data**

Dec. 15, 1975 Japan 50-148443

[52] U.S. Cl. **260/37 SB; 260/46.5 R; 260/46.5 UA**

[51] Int. Cl.² **C08L 83/04**

[58] Field of Search **260/37 SB, 46.5 R**

[56]

References Cited

UNITED STATES PATENTS

3,131,161	4/1964	Nitzsche et al.	260/37 SB
3,205,197	9/1965	Cohen et al.	260/37 SB X
3,455,877	7/1969	Plueddemann	260/46.5 R

Primary Examiner—Lewis T. Jacobs

Attorney, Agent, or Firm—Robert L. McKellar

[57]

ABSTRACT

There is disclosed heat curable organopolysiloxane compositions which contain adhesion additives which are organosilicon compounds which contain an epoxy functional group and at least one alkyl group or low molecular weight alkenyl group or hydrogen atom bound to silicon.

2 Claims, No Drawings